Docket No.: JCLA17063D-C!P2

RECORDATION FORM	COVER SHEET  U. S. Department of Commerce Patent and Trademark Office	
PATENTS ONLY  To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.		
GENG-SHIN SHEN, June 18, 2008  DAVID WEI WANG, June 18, 2008	(1). ChipMOS TECHNOLOGIES INC.  NO. 1, R&D 1ST RD., SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN, R.O.C.	
	(2). ChipMOS TECHNOLOGIES (BERMUDA) LTD.	
3. Nature of conveyance:   x Assignment Security Agreement  Merger Change of Name	CANON'S COURT, 22 VICTORIA STREET, HAMILTON HM 12, BERMUDA	
Reassignment Other	Add'1 names of receiving parties Attached? Yes X No	
<ol><li>Application number(s) or patent number(s):</li></ol>		
A. Patent Application No. (s)	B. Patent No.(s)	
12/169,132		
Additional number attached?		
<ol><li>Name and address of party to whom correspondence concerning document should be mailed:</li></ol>	6. Total No. of applications and patents involved:  ONE ( 1 )	
	7. Total fee(37CFR§3.41): \$ 40.00	
J. C. Patents 4 Venture, Suite 250	Authorized to be charged by credit card	
Irvine, CA 92618	x Authorized to be charge to deposit account	
(949) 660-0761	Enclosed	
i	None required (government interest not affecting title)  8. Payment Information	
	a. Credit Card Last 4 Numbers Expiration Date	
	b. Deposit Account Number 50-0710	
Atty Docket No.: JCLA17063D-CIP2  3. Statement and Signature:	Authorized User Name <u>Jiawei Huang</u>	
5. Statement and Signature.		
To the best of my knowledge and be Correct and any attached copy is a t	elief, the forging information is true and true copy of the original document.	
Jiawei Huang	7-8-2008 Total number of pages including cover sheet,	
Name of person Signing Signature Registration No. 43,330	Date attachments, and documents: 3	

PATENT REEL: 021210 FRAME: 0685 ID-200505005-a4 17063-US-PA-1P2

#### ASSIGNMENT

WHEREAS, 1. Geng-Shin Shen

2. David Wei Wang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: CHIP PACKAGE

[ ] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, 1. ChipMOS Technologies Inc.

of No. 1, R&D 1st Rd., Science-Based Industrial Park Hsinchu, Taiwan, R.O.C.

2. ChipMOS Technologies (Bermuda) Ltd.

of Canon's Court, 22 Victoria Street, Hamilton HM12, Bermuda

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ID-200505005-a4 17063-US-PA-1P2

# **ASSIGNMENT CONTINUED**

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Gent-ohin Slun Date: Jun/18 as Signature:

Sole or First Joint Inventor: Geng-Shin Shen

Signature:

Date:\_

Second Joint Inventor (if any): David Wei Wang/

## J.C. PATENTS

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#### CERTIFICATE OF TRANSMISSION

### July 8, 2008

Atty Docket No.	:	JCLA17063D-CIP2
Appl. No.	:	12/169,132
Filing Date	:	July, 08, 2008
Pages	:	Cover + 3

## BY FACSIMILE ONLY

:   571-273-0140
: MAIL STOP Assignment Commissioner for Patents
: Jiawei Huang, Reg. No. 43,330
: Enclosed herewith is a Recordation Cover Sheet with Assignment in 3 pages.

Sir:

I hereby certify that this correspondence is being facsimile transmitted to the Patent and Trademark Office on **July 8, 2008** at the above indicated fax number.

Sign by

Michelle Chang

**RECORDED: 07/08/2008** 

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PATENT

REEL: 021210 FRAME: 0688